IGBT 600V, 4.5A, N-Channel



ON Semiconductor®

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Features

- Reverse Conducting II IGBT
- IGBT VCE(sat)=1.7V (typ) [IC=3A, VGE=15V]
- IGBT t_f=75ns (typ)
- Diode V_F=1.5V (typ) [I_F=3A]
- Diode t_{rr}=65ns (typ)
- 5μs Short Circuit Capability

Applications

• General Purpose Inverter

Specifications

Absolute Maximum Ratings at Ta=25°C, Unless otherwise specified

Paramete	Symbol	Value	Unit	
Collector to Emitter Voltage	VCES	600	V	
Gate to Emitter Voltage	VGES	±20	V	
Collector Current (DC) @Tc=25°C *2			9	Α
Limited by Tjmax	@Tc=100°C *2	IC *1	4.5	Α
Collector Current (Peak) Pulse width Llimited by Tjma	ICP	12	А	
Diode Average Output Curre	lo	4.5	Α	
Power Dissipation Tc=25°C (Our ideal heat dissi	PD	49	W	
Junction Temperature	Tj	175	°C	
Storage Temperature	Tstg	–55 to +175	°C	

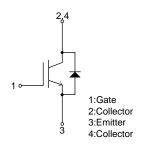
Note: *1 Collector Current is calculated from the following formula.

$$I_{C}(Tc) = \frac{Tjmax - Tc}{R_{th}(j-c) \times V_{CE}(sat) (I_{C}(Tc))}$$

*2 Our condition is radiation from backside.

The method is applying silicone grease to the backside of the device and attaching the device to water-cooled radiator made of aluminum.

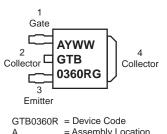
Electrical Connection N-Channel





DPAK CASE 369C

Marking Diagram



 A
 = Assembly Location

 Y
 = Year

 WW
 = Work Week

 G
 = Pb-Free Package

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

ORDERING INFORMATION

See detailed ordering and shipping information on page 8 of this data sheet.

Electrical Characteristics at Ta=25°C, Unless otherwise specified

Dozometer	Cymphol	ool Conditions		Value			Unit
Parameter	Symbol			min	typ	max	Unit
Collector to Emitter Breakdown Voltage	V(BR)CES	I _C =1mA, V _{GE} =0V		600			٧
Collector to Emitter Cut off Current		.,	Tc=25°C			10	μΑ
Collector to Emiliter Cut oil Current	ICES	VCE=600V, VGE=0V	Tc=150°C			1	mA
Gate to Emitter Leakage Current	IGES	V _{GE} =±20V, V _{CE} =0V				±100	nA
Gate to Emitter Threshold Voltage	V _{GE} (th)	V _{CE} =20V, I _C =80μA		4.5		7.0	٧
Collector to Emitter Seturation Valtage	\/a=()	Va= 45V la 2A	Tc=25°C		1.7	2.1	V
Collector to Emitter Saturation Voltage	VCE(sat)	V _{GE} =15V, I _C =3A	Tc=100°C		1.9	2.3	V
Forward Diode Voltage	VF	IF=3A			1.5	2.1	٧
Input Capacitance	Cies				415		pF
Output Capacitance	Coes	V _{CE} =20V, f=1MHz			17		pF
Reverse Transfer Capacitance	Cres				10		pF
Turn-ON Delay Time	t _d (on)	- V _{CC} =300V, I _C =3A R _G =30Ω, L=500μH V _{GE} =0V/15V Vclamp=400V T _C =25°C See Fig.1, See Fig.2			27		ns
Rise Time	t _r				17		ns
Turn-ON Time	ton				85		ns
Turn-OFF Delay Time	t _d (off)				59		ns
Fall Time	tf				75		ns
Turn-OFF Time	toff				172		ns
Turn-ON Energy	Eon				50		μJ
Turn-OFF Energy	Eoff			27		μJ	
Total Gate Charge	Qg	VCE=300V, VGE=15V, IC=3A			17		nC
Gate to Emitter Charge	Qge				4.4		nC
Gate to Collector "Miller" Charge	Qgc				7.6		nC
Diode Reverse Recovery Time	t _{rr}	I _F =3A,di/dt=200A/μs, V _{CC} =300V, See Fig.3			65		ns

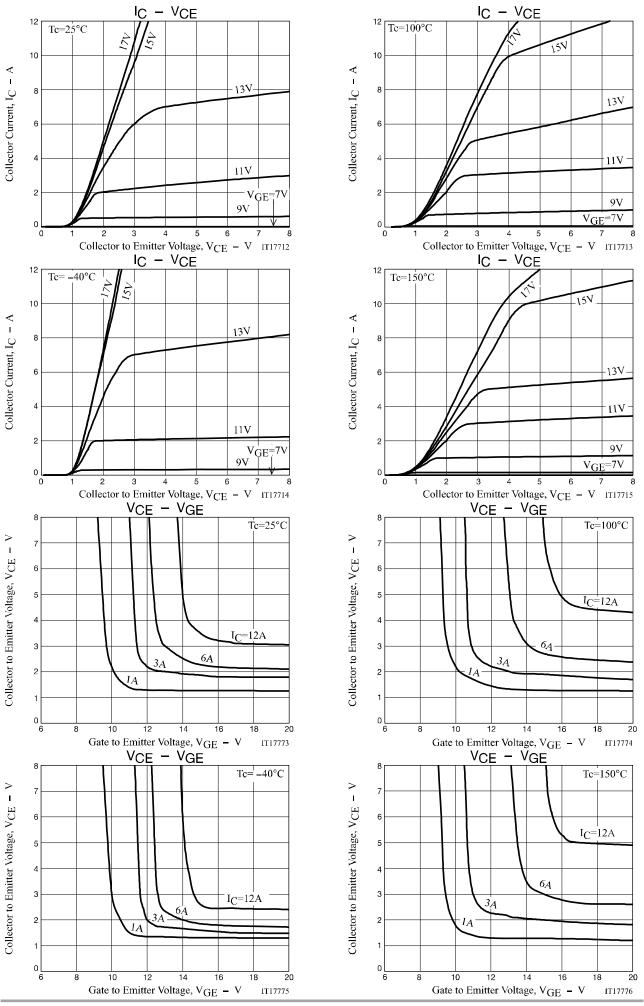
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

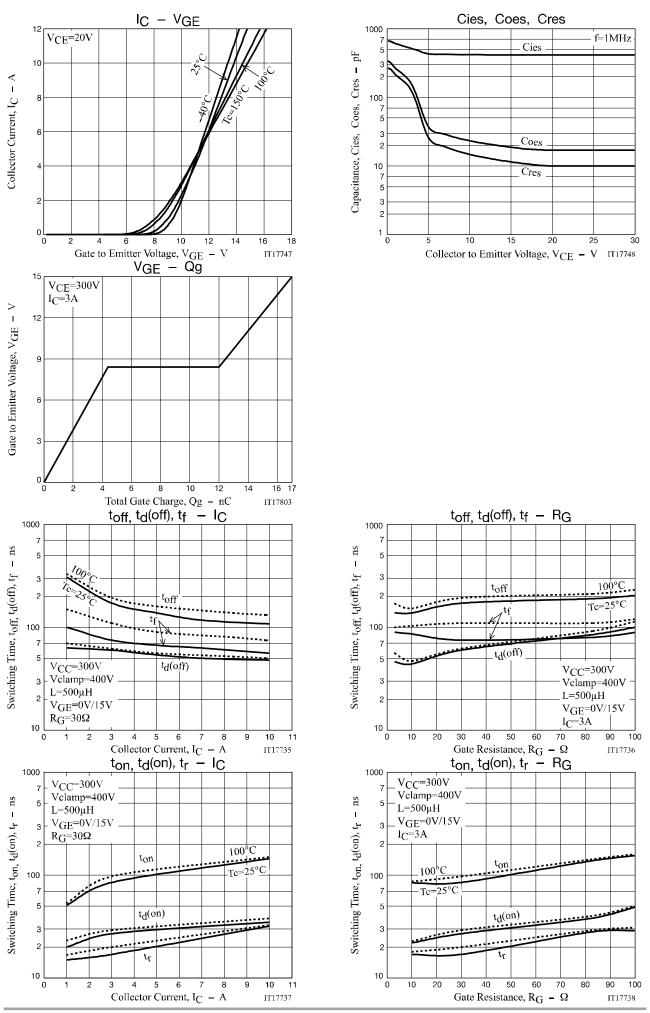
Thermal Characteristics at Ta=25°C, Unless otherwise specified

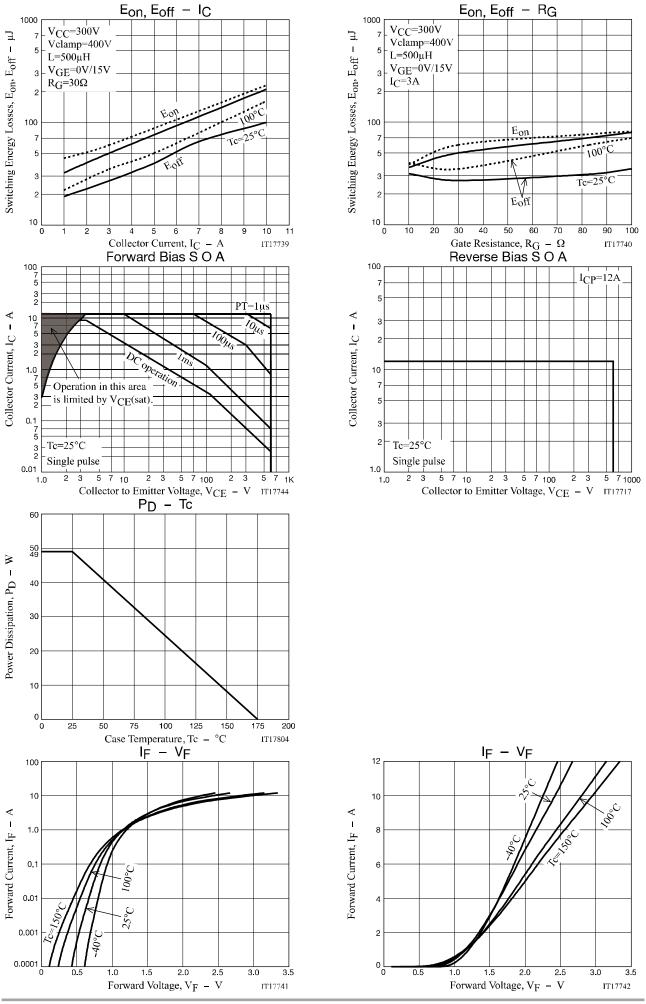
Parameter	Symbol	Conditions	Value	Unit
Thermal Resistance IGBT (Junction to Case)	Rth(j-c) (IGBT)	Tc=25°C (Our ideal heat dissipation condition) *2	3.06	°C/W
Thermal Resistance (Junction to Ambient)	Rth(j-a)		100	°C/W

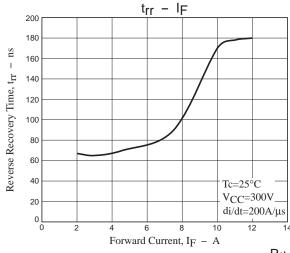
Note: *2 Our condition is radiation from backside.

The method is applying silicone grease to the backside of the device and attaching the device to water-cooled radiator made of aluminum.









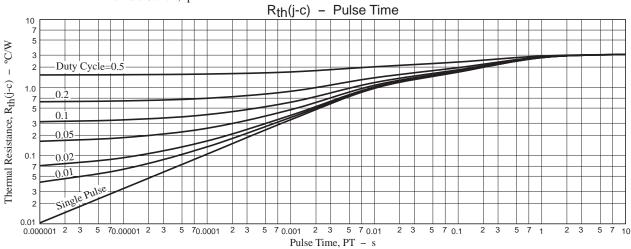


Fig.1 Switching Time Test Circuit

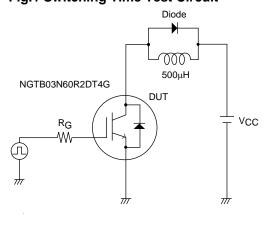


Fig.2 Timing Chart

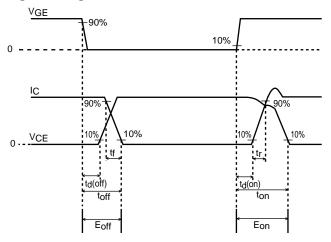
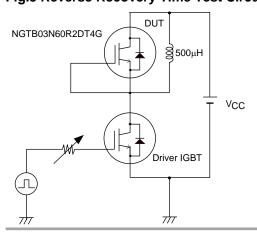


Fig.3 Reverse Recovery Time Test Circuit

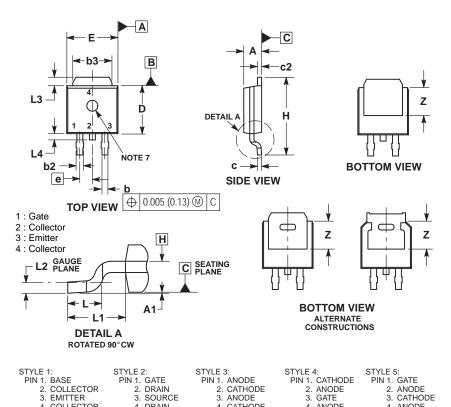


Package Dimensions

DPAK (SINGLE GAUGE)

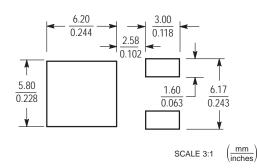
2. COLLECTOR 3. EMITTER

CASE 369C ISSUE F



4. COLLE	CTOR	4. DRAIN	4. CATE	HODE	4. ANODE	4.	ANODE
STYLE 6:	STYLE 7:	STYLE	8:	STYLE 9:		STYLE '	10:
PIN 1. MT1	PIN 1. GATE	PIN 1.	. N/C	PIN 1. AN	ODE	PIN 1.	CATHODE
2. MT2	COLLI	ECTOR 2	CATHODE	2. CA	THODE	2.	ANODE
GATE	EMITT	ER 3.	ANODE	3. RE	SISTOR ADJUST	3.	CATHODE
4. MT2	COLLI	ECTOR 4.	CATHODE	4. CA	THODE	4.	ANODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

- IOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: INCHES.
 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
- MENSIONS b3, L3 and Z.

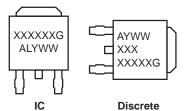
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.

 5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.

 6. DATUMS A AND B ARE DETERMINED AT DATUM DI ANE H
- PLANE H.
- 7. OPTIONAL MOLD FEATURE.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.086	0.094	2.18	2.38	
A1	0.000	0.005	0.00	0.13	
b	0.025	0.035	0.63	0.89	
b2	0.028	0.045	0.72	1.14	
b3	0.180	0.215	4.57	5.46	
С	0.018	0.024	0.46	0.61	
c2	0.018	0.024	0.46	0.61	
D	0.235	0.245	5.97	6.22	
E	0.250	0.265	6.35	6.73	
е	0.090	BSC	2.29 BSC		
Н	0.370	0.410	9.40	10.41	
L	0.055	0.070	1.40	1.78	
L1	0.114 REF		2.90 REF		
L2	0.020 BSC		0.51 BSC		
L3	0.035	0.050	0.89	1.27	
L4		0.040		1.01	
Z	0.155		3.93		

GENERIC MARKING DIAGRAM*



XXXXXX = Device Code Α = Assembly Location = Wafer Lot = Year WW = Work Week = Pb-Free Package G

*This information is generic. Please refer to device data sheet for actual part marking.

ORDERING INFORMATION

Device	Marking	Package	Shipping (Qty / Packing)
NGTB03N60R2DT4G	AYWW GTB 0360RG	DPAK (SINGLE GAUGE) (Pb-Free / Halogen Free)	2500 / Tape & Reel

[†] For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. http://www.onsemi.com/pub_link/Collateral/BRD8011-D.PDF

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 TIG058E8-TL-H
 VS-CPV364M4KPBF
 NGTB25N120FL2WAG
 NGTG40N120FL2WG
 RJH60F3DPQ-A0#T0

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 APT35GP120JDQ2

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 IKFW50N65ES5XKSA1
 IKFW50N65EH5XKSA1
 IKFW40N65ES5XKSA1

 IKFW60N65ES5XKSA1
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 XD25H120CX0
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 IGW75N60H3FKSA1
 HGTG40N60B3
 FGH60N60SMD_F085

 FGH75T65UPD
 STGWA15H120F2
 IKA10N60TXKSA1
 IHW20N120R5XKSA1
 RJH60D2DPP-M0#T2
 IKP20N60TXKSA1

 IHW20N65R5XKSA1
 IDW40E65D2FKSA1